

VERSION WITH MARKINGS TO SHOW CHANGES MADE

1. (Twice Amended) A semiconductor device, comprising:

a bumped device having a plurality of conductive bumps formed thereon;

a substrate having a plurality of pockets disposed therein and a plurality of metallic contact pads distributed thereon and approximately aligned with the plurality of conductive bumps, each contact pad being at least partially disposed within one of the pockets; and

an anisotropically conductive layer disposed between and mechanically coupled to the bumped device and to the substrate, the anisotropically conductive layer electrically coupling each of the conductive bumps with a corresponding one of the contact pads.

9. (Twice Amended) An apparatus for testing a bumped device having a plurality of conductive bumps, comprising:

a substrate including a first surface having a plurality of pockets disposed therein and a plurality of metallic contact pads distributed thereon, the contact pads being substantially alignable with the plurality of conductive bumps, each contact pad being at least partially disposed within one of the pockets; and

an anisotropically conductive layer disposed on the first surface and engageable with the plurality of conductive bumps to electrically couple each of the conductive bumps with a corresponding one of the contact pads.